

# STL42P6LLF6-VB Datasheet

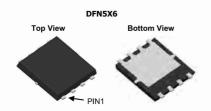
-60V Single-P Trench DFN8(5X6) MOSFET

PRODUCT SUMMARY			
V <sub>DS</sub> (V)	-60		
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS}$ = -10 V	0.0210		
$R_{DS(on)}$ ( $\Omega$ ) at $V_{GS} = -4.5 \text{ V}$	0.0288		
I <sub>D</sub> (A)	-36		
Configuration	Single		
Package	DFN 5X6		

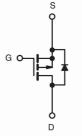
#### **FEATURES**

- TrenchFET® power MOSFET
- 100 % R<sub>g</sub> and UIS tested









P-Channel MOSFET

<b>ABSOLUTE MAXIMUM RATINGS</b> (T <sub>C</sub> = 25 °C, unless otherwise noted)					
PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-Source Voltage		V <sub>DS</sub>	-60	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current	T <sub>C</sub> = 25 °C		-36		
	T <sub>C</sub> = 125 °C	l <sub>D</sub>	-21		
Continuous Source Current (Diode Conduction) <sup>a</sup>		Is	-60	A	
Pulsed Drain Current <sup>b</sup>		I <sub>DM</sub>	-100		
Single Pulse Avalanche Current	L = 0.1 mH	I <sub>AS</sub>	-36		
Single Pulse Avalanche Energy		E <sub>AS</sub>	64.8	mJ	
Maximum Power Dissipation <sup>b</sup>	T <sub>C</sub> = 25 °C	D_	68	W	
	T <sub>C</sub> = 125 °C	- P <sub>D</sub>	22		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	-55 to +175	°C	
Soldering Recommendations (Peak Temperature) d, e			260		

THERMAL RESISTANCE RATINGS				
PARAMETER		SYMBOL	LIMIT	UNIT
Junction-to-Ambient	PCB Mount <sup>c</sup>	R <sub>thJA</sub>	68	°C/W
Junction-to-Case (Drain)		R <sub>thJC</sub>	2.2	C/VV

#### Notes

- a. Package limited.
- b. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %. c. When mounted on 1" square PCB (FR4 material).

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<b>SPECIFICATIONS</b> ( $T_C = 25$ °C,	unless otherv	/ise noted)					
PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static	1				_		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0$ , $I_D = -250 \mu A$		-60	-	-	V
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> =	$V_{DS} = V_{GS}, I_{D} = -250 \mu A$		-2.0	-2.5	, v
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$		-	-	± 100	nA
Zero Gate Voltage Drain Current		$V_{GS} = 0 V$	V <sub>DS</sub> = -60 V	-	-	-1	
	I <sub>DSS</sub>	$V_{GS} = 0 V$	V <sub>DS</sub> = -60 V, T <sub>J</sub> = 125 °C	-	-	-50	μA
		$V_{GS} = 0 V$	V <sub>DS</sub> = -60 V, T <sub>J</sub> = 175 °C	-	-	-150	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	V <sub>GS</sub> = -10 V	$V_{DS} \ge -5 \text{ V}$	-30	-	-	Α
		V <sub>GS</sub> = -10 V	I <sub>D</sub> = -10 A	-	0.0210	-	
Drain-Source On-State Resistance a	D	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -10 A, T <sub>J</sub> = 125 °C	-	0.0409	-	Ω
Drain-Source On-State Resistance 4	R <sub>DS(on)</sub>	V <sub>GS</sub> = -10 V	I <sub>D</sub> = -10 A, T <sub>J</sub> = 175 °C	-	0.0504	-	
		V <sub>GS</sub> = -4.5 V	I <sub>D</sub> = -5 A	-	0.0288	-	
Forward Transconductance b	9 <sub>fs</sub>	V <sub>DS</sub> = -15 V, I <sub>D</sub> = -10 A		-	26	-	S
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>		V <sub>DS</sub> = -25 V, f = 1 MHz	-	2600	3400	pF
Output Capacitance	C <sub>oss</sub>	$V_{GS} = 0 V$		-	310	450	
Reverse Transfer Capacitance	C <sub>rss</sub>			-	200	275	
Total Gate Charge <sup>c</sup>	Qg			-	65	100	
Gate-Source Charge <sup>c</sup>	Q <sub>gs</sub>	V <sub>GS</sub> = -10 V	$V_{DS} = -30 \text{ V}, I_{D} = -5 \text{ A}$	-	9.5	-	nC
Gate-Drain Charge <sup>c</sup>	Q <sub>gd</sub>			-	19	-	
Gate Resistance	Rg	f = 1 MHz		0.50	1.19	1.80	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			-	15	25	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = -30 \text{ V, } R_L = 6 \Omega$ $I_D \cong -5 \text{ A, } V_{GEN} = -10 \text{ V, } R_g = 1 \Omega$		-	5	10	ns
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>			-	40	75	
Fall Time <sup>c</sup>	t <sub>f</sub>			-	6	12	
Source-Drain Diode Ratings and Char	acteristics <sup>b</sup>						
Pulsed Current <sup>a</sup>	I <sub>SM</sub>			-	-	-100	Α
Forward Voltage	V <sub>SD</sub>	I <sub>F</sub> = -10 A, V <sub>GS</sub> = 0 V		-	-0.80	-1.2	V

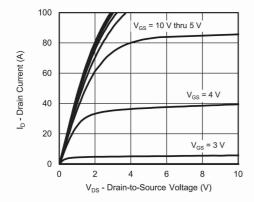
### Notes

- a. Pulse test; pulse width  $\leq$  300 µs, duty cycle  $\leq$  2 %. b. Guaranteed by design, not subject to production testing. c. Independent of operating temperature.

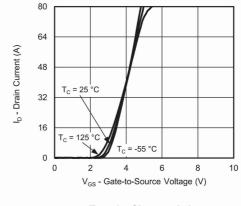
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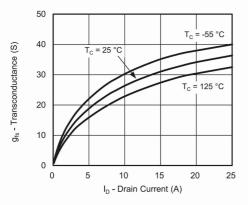
# **TYPICAL CHARACTERISTICS** ( $T_A = 25$ °C, unless otherwise noted)



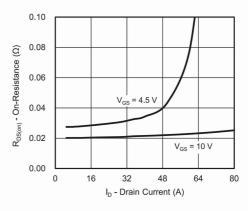




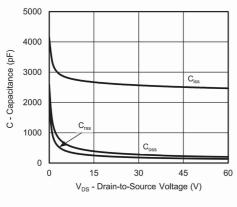
**Transfer Characteristics** 



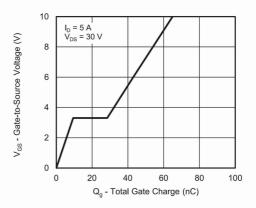
Transconductance



On-Resistance vs. Drain Current



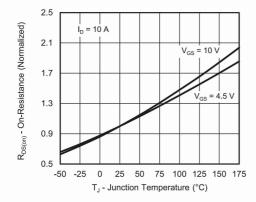
Capacitance



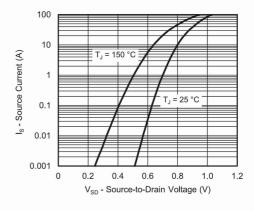
**Gate Charge** 



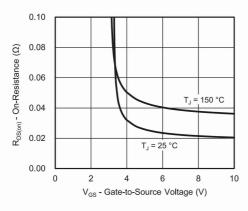
### TYPICAL CHARACTERISTICS (T<sub>A</sub> = 25 °C, unless otherwise noted)



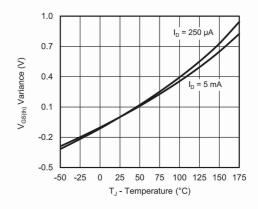
On-Resistance vs. Junction Temperature



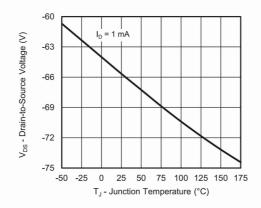
Source Drain Diode Forward Voltage



On-Resistance vs. Gate-to-Source Voltage



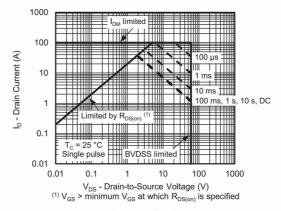
Threshold Voltage



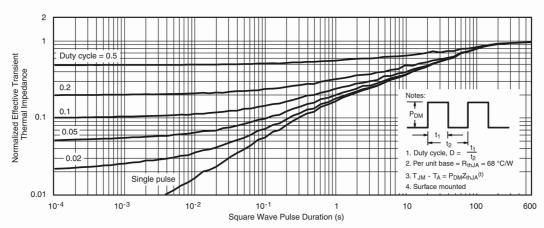
Drain-Source Breakdown vs. Junction Temperature



## **THERMAL RATINGS** ( $T_C = 25$ °C, unless otherwise noted)



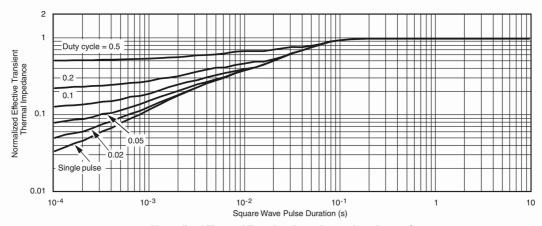
#### Safe Operating Area



Normalized Thermal Transient Impedance, Junction-to-Ambient



### **THERMAL RATINGS** (T<sub>C</sub> = 25 °C, unless otherwise noted)



#### Normalized Thermal Transient Impedance, Junction-to-Case

#### Note

- · The characteristics shown in the two graphs
  - Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
  - Normalized Transient Thermal Impedance Junction-to-Case (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



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